



40V N-Channel MOSFETs

General Description

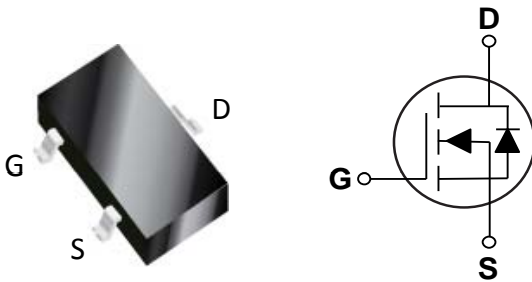
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
40 V	33 mΩ	5 A

Features

- R_{DS(ON)}=33mΩ@V_{GS}=10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

SOT-23S Pin Configuration



Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current - Continuous (T _c =25°C)	5	A
	Drain Current - Continuous (T _c =100°C)	3	A
I _{DM}	Drain Current - Pulsed (NOTE 1)	20	A
P _D	Power Dissipation (T _c =25°C)	1.56	W
	Power Dissipation - Derate above 25°C	0.012	W/°C
T _J	Operating Junction Temperature Range	-50 to 150	°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
Marking Code		f	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to Ambient	---	80	°C/W

**Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=32V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance (NOTE 3)	$V_{GS}=10V, I_D=2A$	---	26	33	m Ω
		$V_{GS}=4.5V, I_D=1.5A$	---	33	45	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
gfs	Forward Transconductance	$V_{DS}=10V, I_D=4A$	---	6	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge	$V_{DS}=20V, V_{GS}=4.5V, I_D=3A$ (NOTE 2 · 3)	---	4.7	8	nC
Q_{gs}	Gate-Source Charge		---	0.45	1	
Q_{gd}	Gate-Drain Charge		---	1.65	3.2	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=20V, V_{GS}=4.5V, R_G=25\Omega$, $I_D=1A$ (NOTE 2 · 3)	---	3.2	6	nS
T_r	Rise Time		---	8.6	16	
$T_{d(off)}$	Turn-Off Delay Time		---	18	36	
T_f	Fall Time		---	6	12	
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	420	800	pF
C_{oss}	Output Capacitance		---	65	120	
C_{riss}	Reverse Transfer Capacitance		---	40	80	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	5	A
I_{SM}	Pulsed Source Current (NOTE 3)		---	---	10	A
V_{SD}	Diode Forward Voltage (NOTE 3)	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_S=1A, di/dt=100A/\mu s$	---	20	---	nS
Q_{rr}	Reverse Recovery Charge	, $T_J=25^\circ\text{C}$	---	7.5	---	nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.



Characteristics Curves

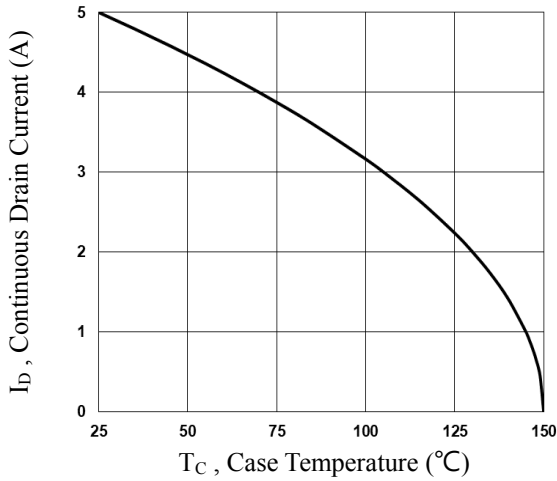


Fig.1 Continuous Drain Current vs. T_C

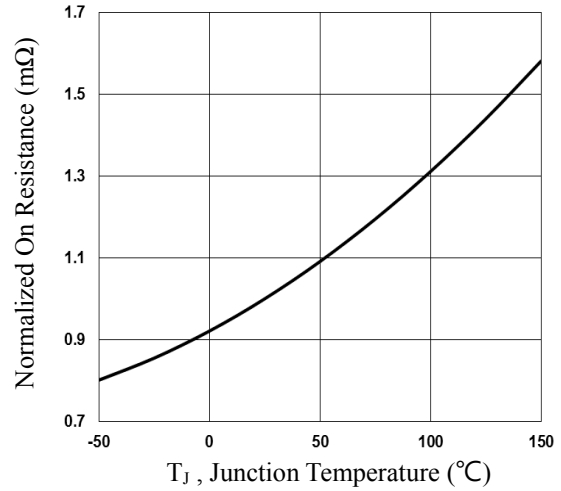


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

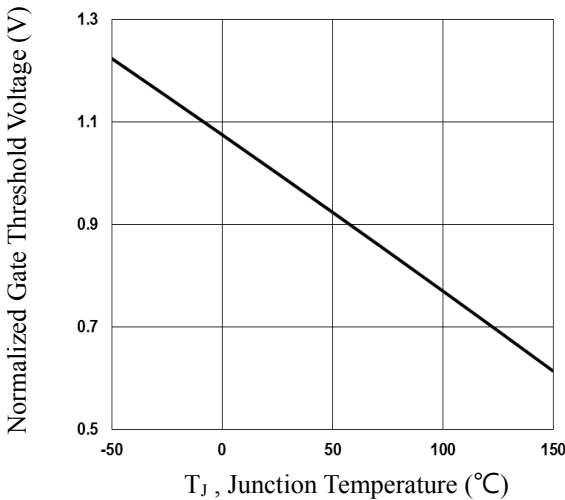


Fig.3 Normalized V_{th} vs. T_J

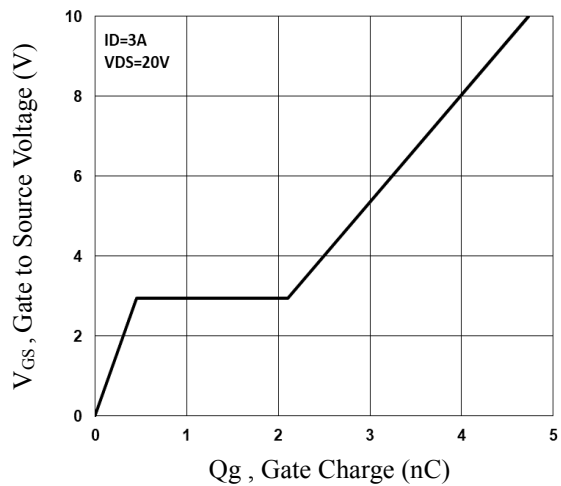


Fig.4 Gate Charge Waveform

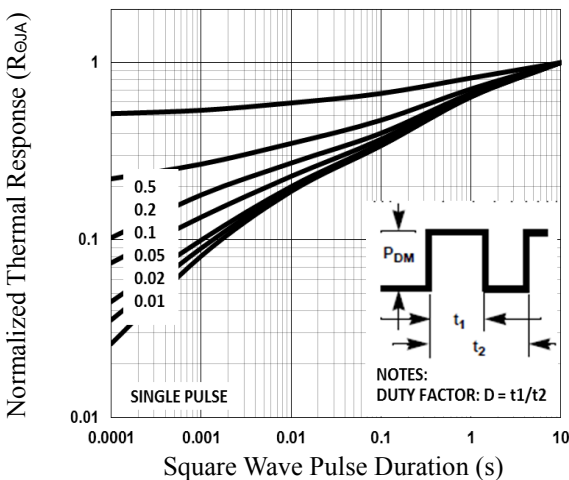


Fig.5 Normalized Transient Response

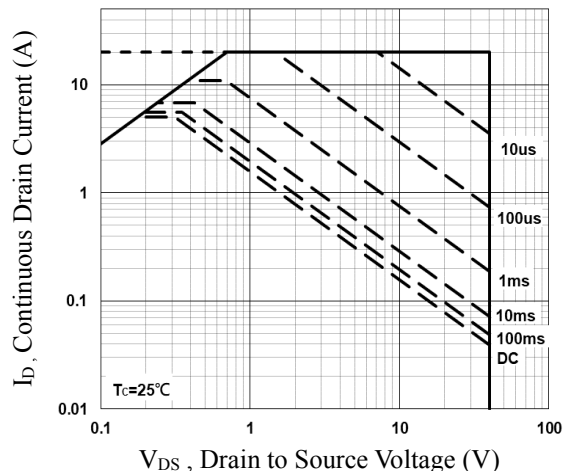


Fig.6 Maximum Safe Operation Area



Characteristics Curves

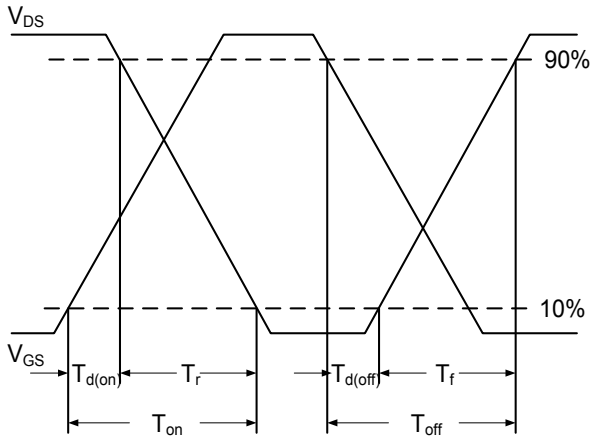


Fig.7 Switching Time Waveform

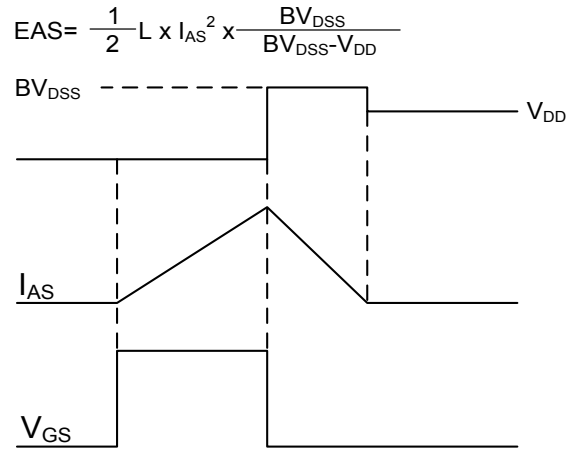
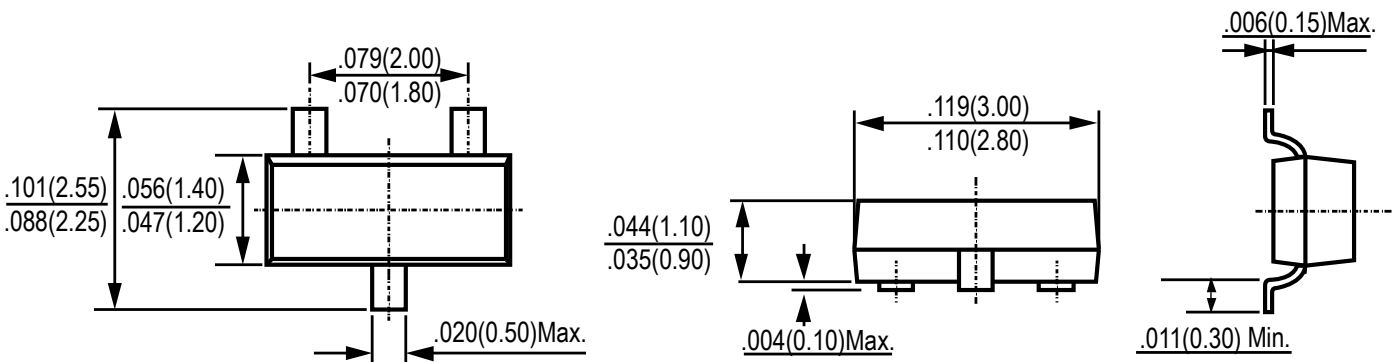


Fig.8 EAS Waveform

Package Outline Dimensions



SOT-23S

Dimensions in inches and (millimeters)



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